

The Challenges of Micro-System Product Development

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<http://www.mems.sandia.gov/>



Sandia is a multiprogram laboratory operated by Sandia Corporation, a Lockheed Martin Company,
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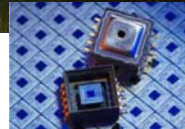
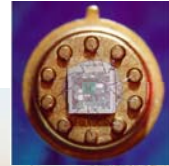




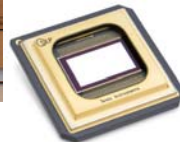
Topics

- **MEMS Products**
- **History**
- **Issues of Scale**
- **Fabrication Processes**
- **Reliability & Problems to be solved**
- **New Applications –Approaches – Problems to be solved**

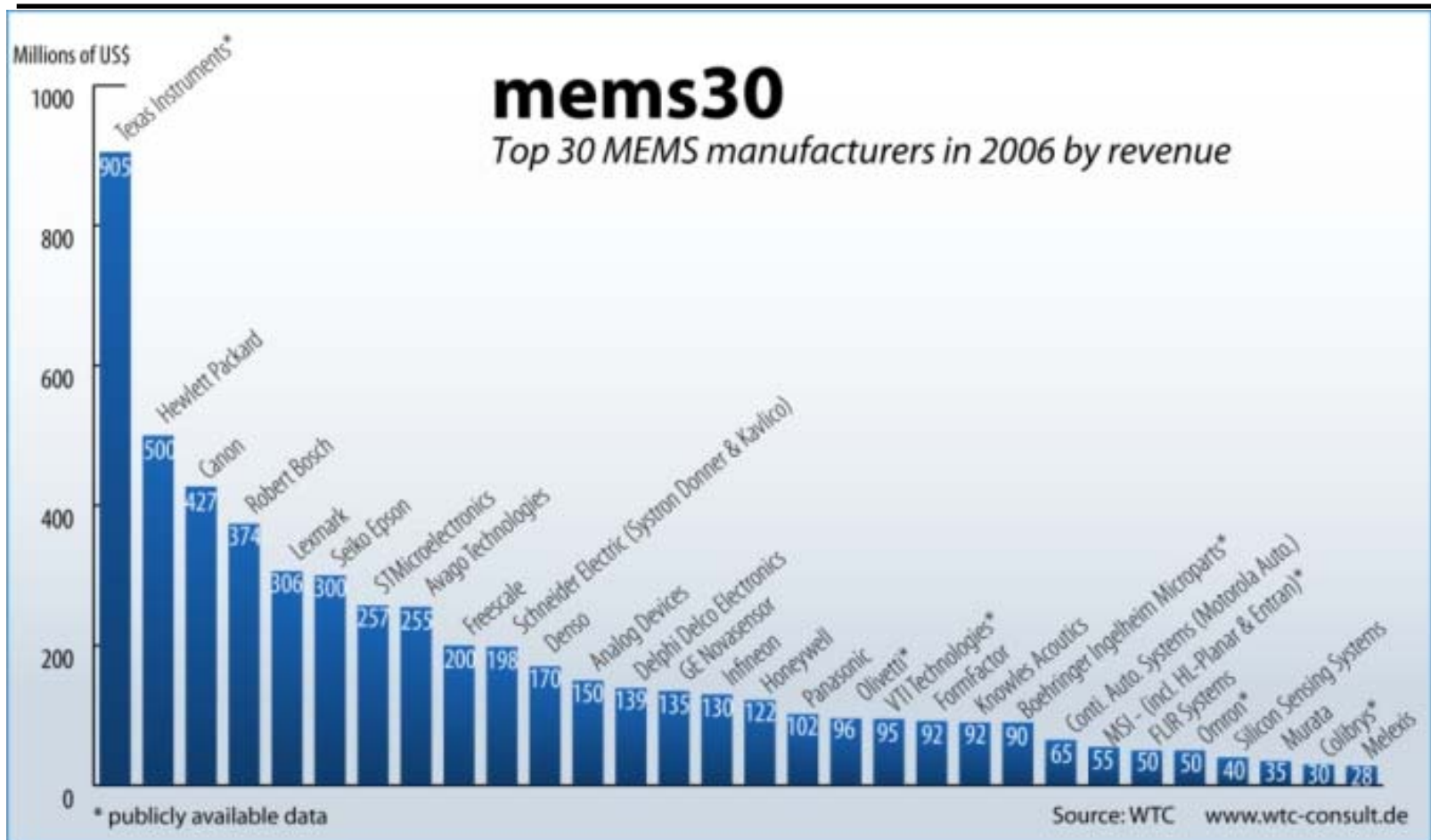
MEMS are everywhere!



QuickTime™ and a
TIFF (Uncompressed) decompressor
are needed to see this picture.



Top MEMS Manufacturers in 2006



- http://www.memsinvestorjournal.com/2007/04/ranking_of_top_.html#more

Vision of Micro-Systems

- **“There’s Plenty of Room at the Bottom”, 1959, California Institute of Technology**

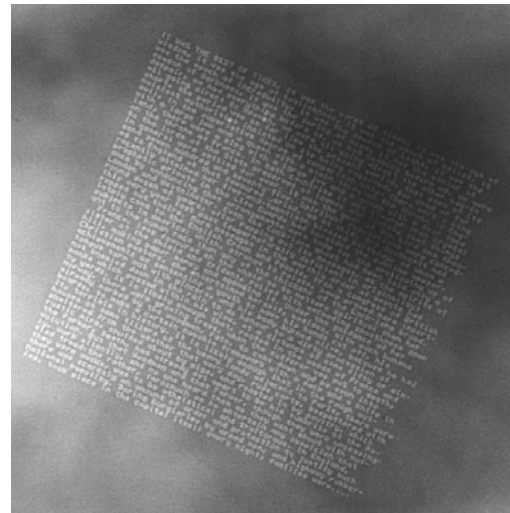
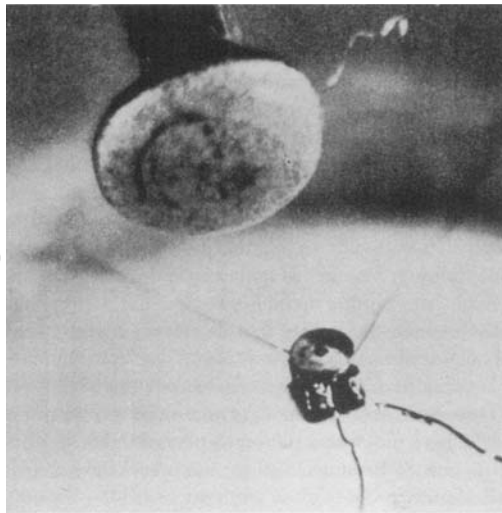
- **2 Challenges:**

- **Construct a working electric motor able to fit in a 1/64 inch cube**
- **Print text at a scale that the Encyclopedia Britannica could fit on the head of a pin**



Richard P. Feynman
(1918-1988)

William McLellan, 1960



T. Newman,
R.F.W. Pease,
1985

The Scale of Things – Nanometers and More

Things Natural



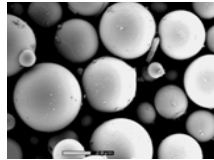
Dust mite
200 μm



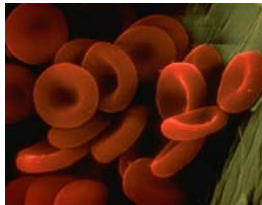
Human hair
~ 60-120 μm wide



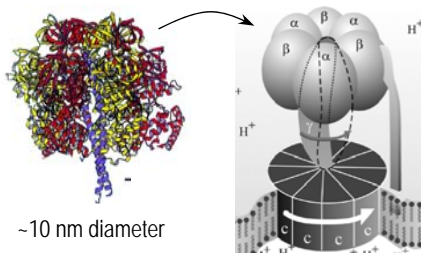
Ant
~ 5 mm



Fly ash
~ 10-20 μm

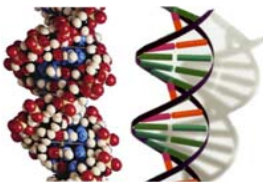


Red blood cells
(~7-8 μm)

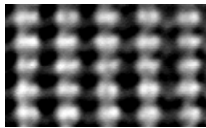


~10 nm diameter

ATP synthase



DNA
~2-1/2 nm diameter

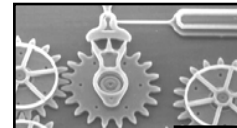


Atoms of silicon
spacing 0.078 nm

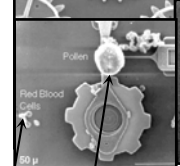
Things Manmade



Head of a pin
1-2 mm

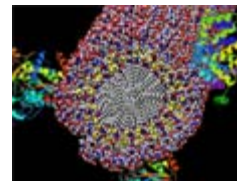


MicroElectroMechanical (MEMS) devices
10 -100 μm wide

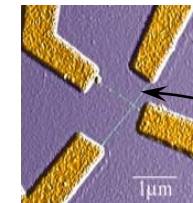


Pollen grain
Red blood cells

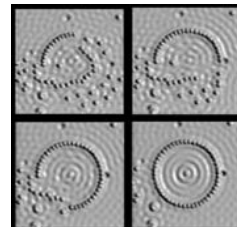
Zone plate x-ray "lens"
Outer ring spacing ~35 nm



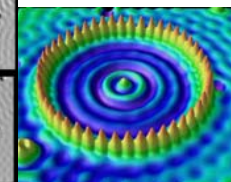
Self-assembled,
Nature-inspired structure
Many 10s of nm



Nanotube electrode

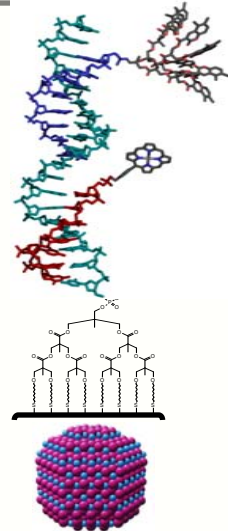


Quantum corral of 48 iron atoms on copper surface
positioned one at a time with an STM tip
Corral diameter 14 nm

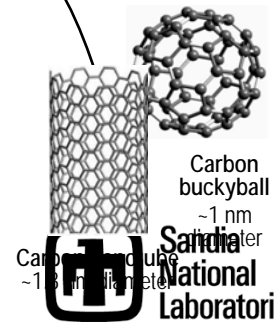


Carbon buckyball
~1 nm diameter

The Challenge



Fabricate and combine nanoscale building blocks to make useful devices, e.g., a photosynthetic reaction center with integral semiconductor storage.

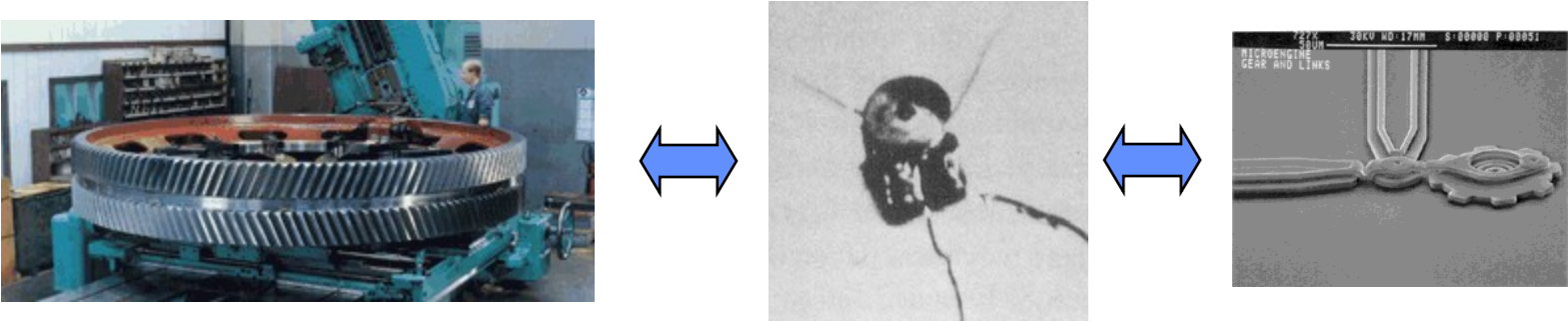


Carbon nanotube
~1 μm diameter

Sandia National Laboratories

Office of Basic Energy Sciences
Office of Science, U.S. DOE
Version 05-26-06, pmd

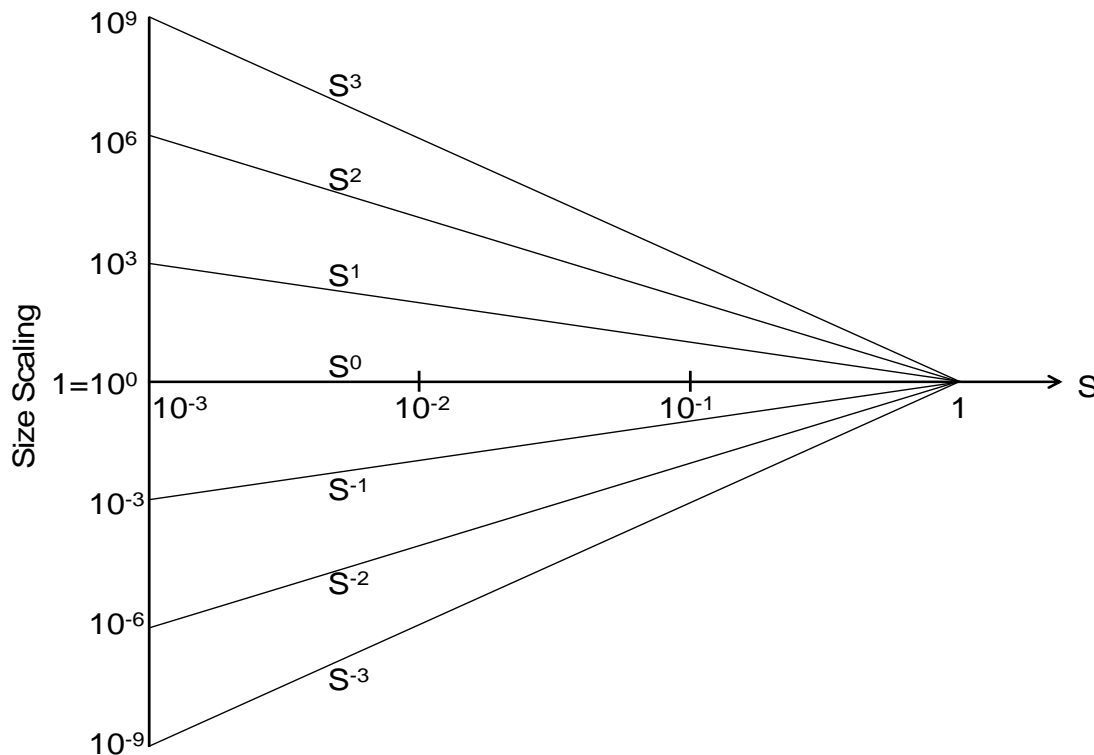
Effect of Reduction in Scale



Why does a change in scale matter?

- Entering different physics regimes at a particular scale.
- Physical phenomena scale at different rates which changes their relative importance.

Use a Scaling Parameter to evaluate Scale effects



$$X_s = S X_o$$

Scaling
Parameter



Geometric Scaling

GEOMETRY SCALING

$$X_s = S X_0$$

$$A_s = X_s Y_s = S^2 X_0 Y_0 = S^2 A_0$$

$$V_s = X_s Y_s Z_s = S^3 X_0 Y_0 Z_0 = S^3 V_0 \quad \longrightarrow \quad \begin{array}{l} \text{Things that depend on} \\ \text{Volume are going to} \\ \text{decrease dramatically} \end{array}$$

AREA – VOLUME RATIO SCALING

$$A_s/V_s = 1/S (A_0/V_0) \quad \longrightarrow \quad \begin{array}{l} \text{Things that depend on} \\ \text{this ratio will increase} \\ \text{in importance} \end{array}$$



Mechanical Scaling

Mass: cubically reduced

$$M_s = \rho S^3 V_o = S^3 M_o$$

Stiffness: Linearly reduced

$$K_{bending} \propto \frac{EI}{L^3} \propto \frac{Ewt^3}{L^3} \propto S$$

$$K_{axial} \propto \frac{EA}{L} \propto \frac{Ewt}{L} \propto S$$

Natural Frequency: increases

$$f_n = \frac{1}{2\pi} \sqrt{\frac{K}{M}} \propto \sqrt{\frac{K}{M}} \propto \sqrt{\frac{S}{S^3}} \propto \frac{1}{S}$$



Thermal Scaling

Thermal Mass: *proportional to volume*

$$mc_p \Delta T = \rho V c_p \Delta T$$

Thermal Conductivity: *Proportional to Area*

$$q = KA \nabla T \quad \text{conduction}$$

$$q = hA (T_w - T_\infty) \quad \text{convection}$$

$$q = A \sigma T^4 \quad \text{radiation}$$

Thermal Diffusivity (time constant): *Proportional to Vol/Area*

$$\tau = \frac{mc_p}{kA} = \left(\frac{\rho c_p}{\kappa} \right) \left(\frac{V}{A} \right) \propto S$$



Fluidic Scaling

Reynolds Number: A measure of the transition between laminar and turbulent flow

Laminar flow: $Re < 2000$

Turbulent Flow: $Re > 4000$



$$Re = \frac{\rho V D}{\mu} \propto S$$

Micro Domain is dominated by laminar flow.



Scaling of Electrical and Magnetic Fields

Energy Density:

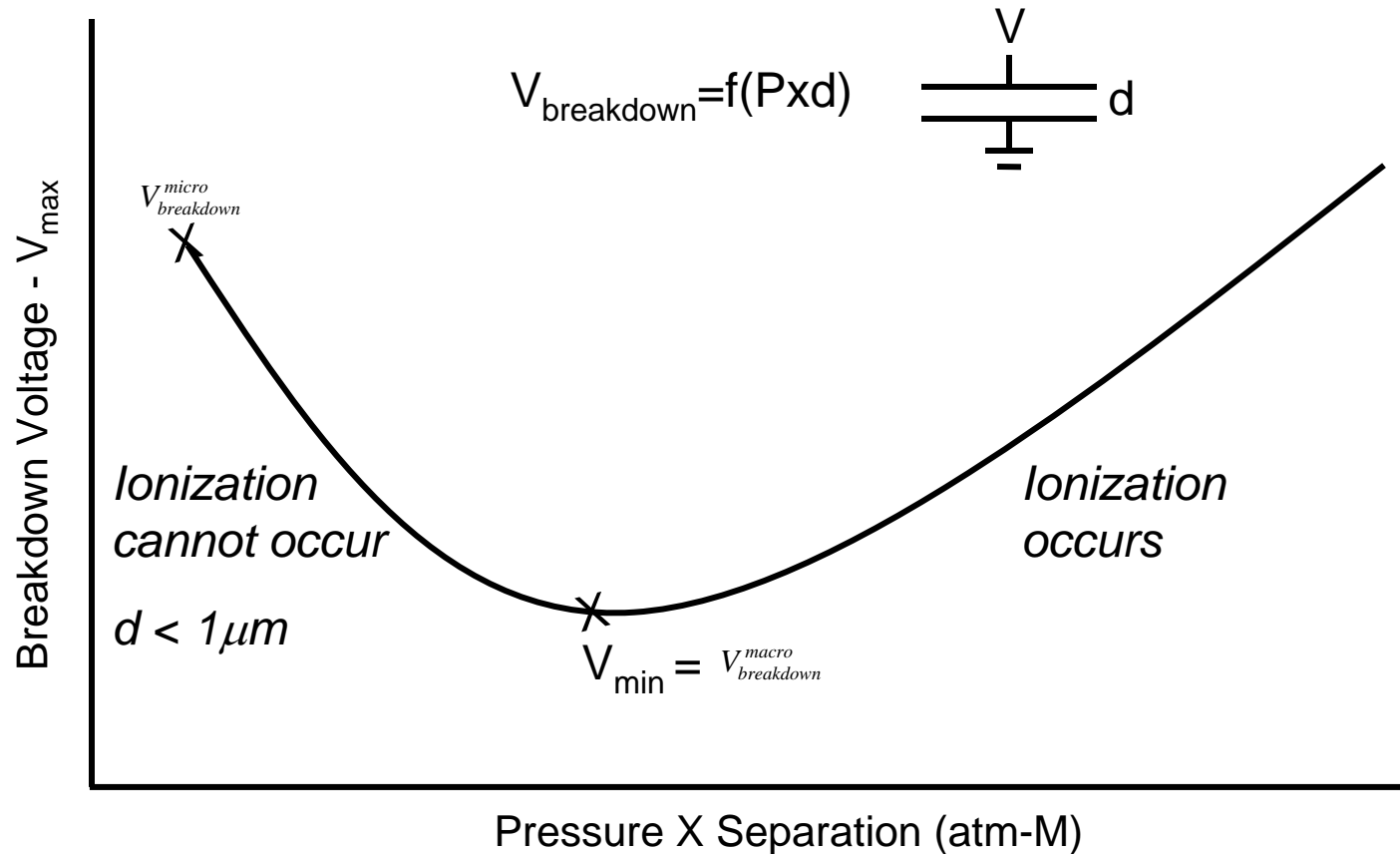
$$U_{electric} = \frac{1}{2} \epsilon E^2 \quad E_{breakdown} = 3 \text{ MV/M} \Rightarrow U_{electric} = 40 \text{ J/M}^3$$

$$U_{magnetic} = \frac{1}{2} \frac{B^2}{\mu} \quad B_{sat} = 1 \text{ T} \Rightarrow U_{mag} = 4 \times 10^5 \text{ J/M}^3$$

Magnetic actuation dominates in the Macro world due to the calculations above.

But Magnetics **does not** dominate in the Micro world.
Why?

Paschen's Law



F. Paschen, Wied. Ann., 37, 69, 1889



Scaling of Electrical and Magnetic Fields

$E_{\text{breakdown}} = 3 \times 10^8 \text{ V/M}$ for small gap of $\sim 1 \text{ } \mu\text{m}$ or less

$$\therefore \Rightarrow U_{\text{electric}} = 4 \times 10^5 \text{ J/M}^3$$

which is now comparable to magnetics

However,

- * Magnetics has fabrication issues at the microscale

- For magnetic field constant $B = B_{\text{sat}}$

- Electric Field increases with decreasing gap ($E \propto \frac{1}{s}$) up to the breakdown voltage.

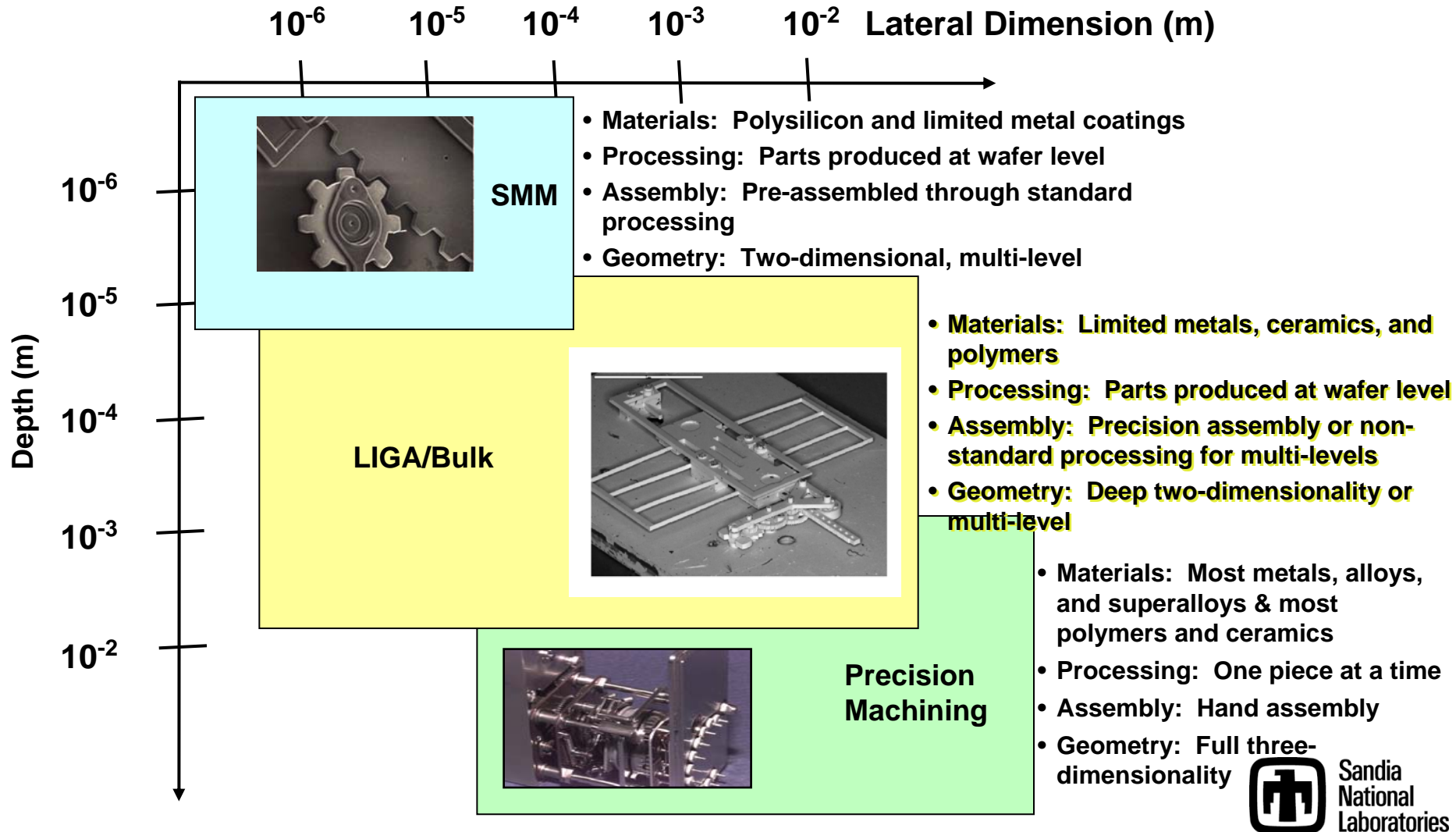


Physical Phenomena Change

The breakdown of the continuum

- Paschen Effect
- M.F.P $0.1 \mu\text{m}$ of air at STP
- Material crystal sizes in polycrystalline material
 $\sim 0.1 \mu\text{m}$
- Magnetic Domains $\sim 10\text{-}25$ micron

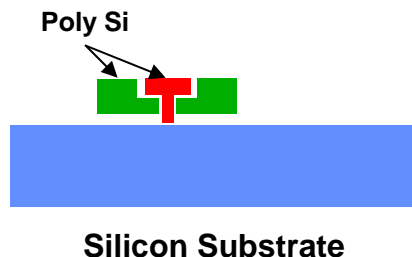
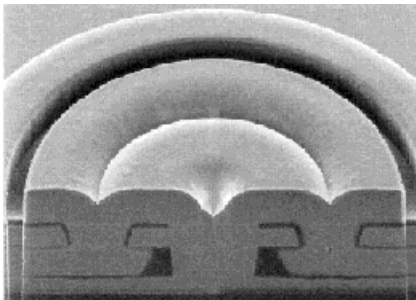
A Continuum of Microsystems Fabrication Technologies



Three Dominant MEMS Fabrication Technologies

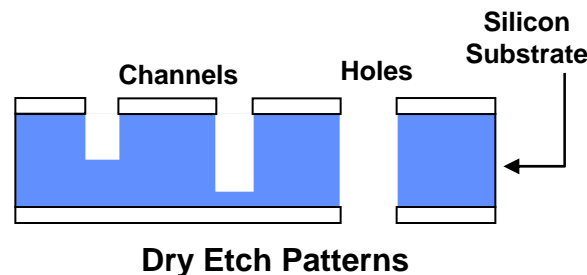
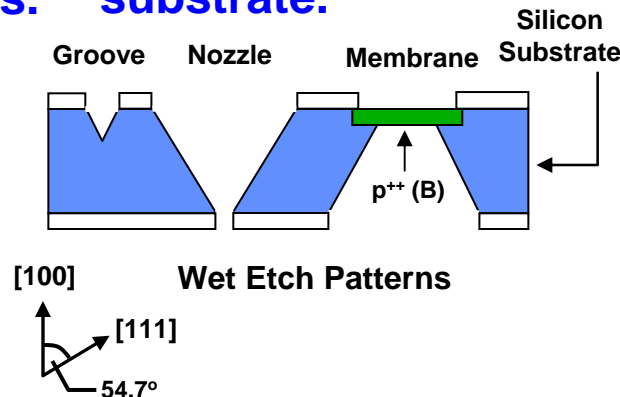
Surface Micromachining

structures formed by deposition and etching of sacrificial and structural thin films.



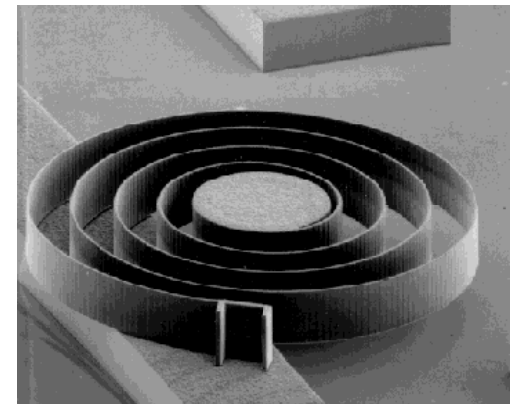
Bulk Micromachining

3D structures formed by wet and/or dry etching of silicon substrate.



LIGA

3D structures formed by mold fabrication, followed by injection molding/electroplating





Manufacturing Effect of Reduction in Scale

• **Size** ↓ **Relative Manufacturing Precision** ↓

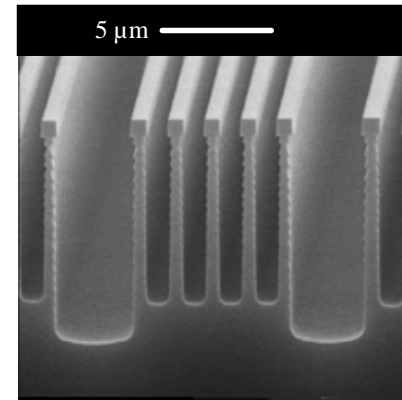
– **Dimensional Tolerance/Nominal Dimension**

- **Micro Scale (1-100 μ m) \approx 0.1% - 1%**

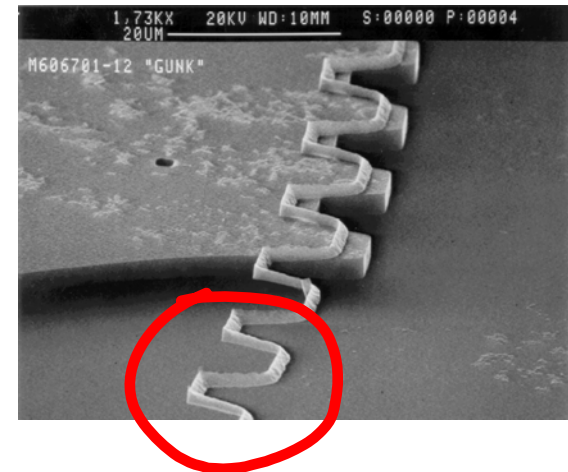
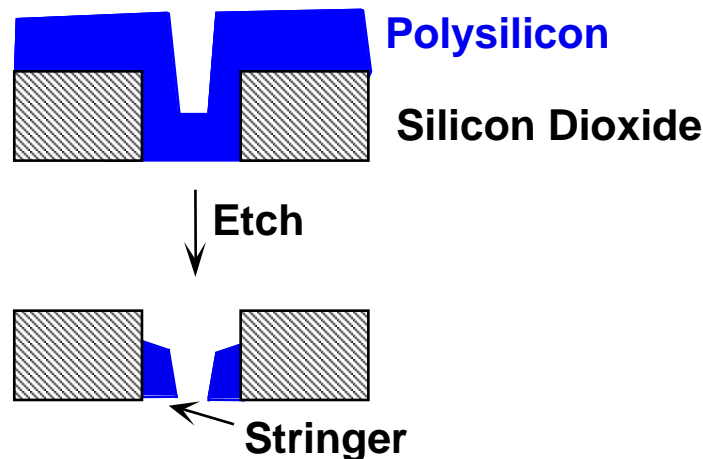
- **Macro Scale (1cm – 1m) \approx 0.001%**

Manufacturing Processes Impose constraints on Design

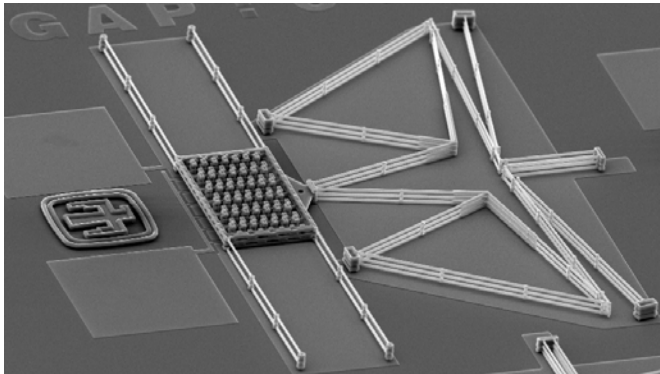
- Bulk Micromaching Example:
 - Aspect ratio of etches



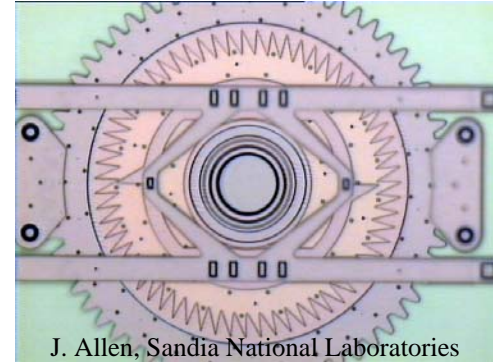
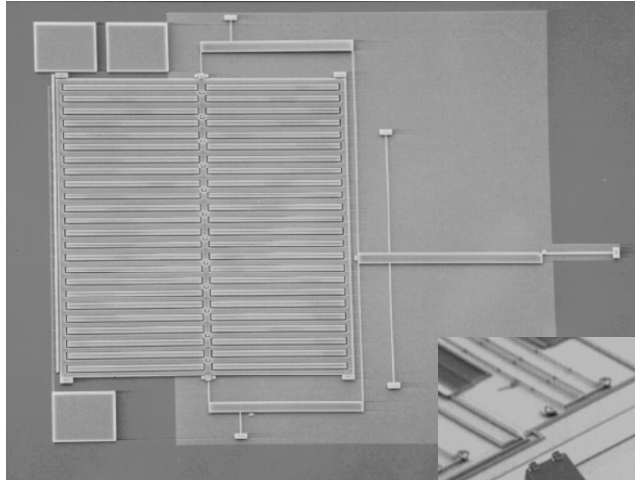
- Surface Micromachining Example
 - Stringers



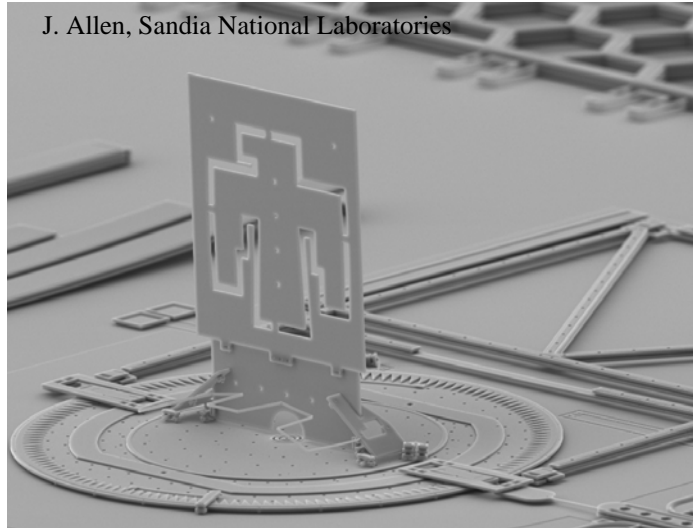
A Variety of Micro Mechanisms are required for Microdevice Applications



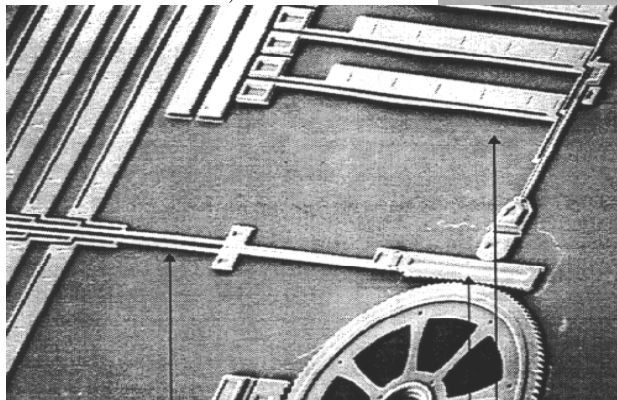
Dr. Kota, U of Michigan, S. Rogers, Sandia National Laboratories



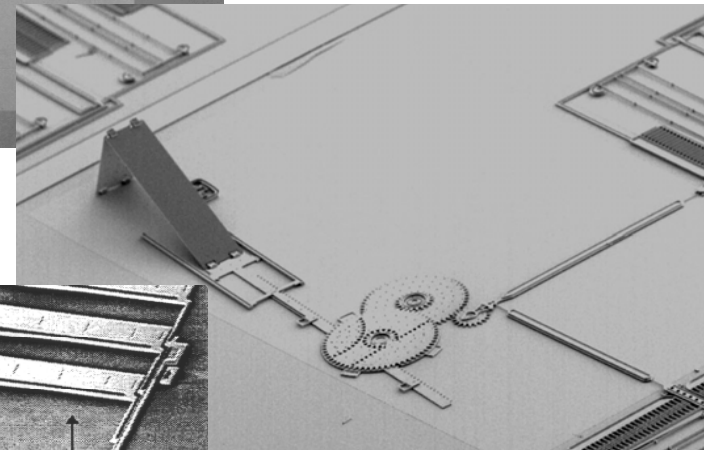
J. Allen, Sandia National Laboratories



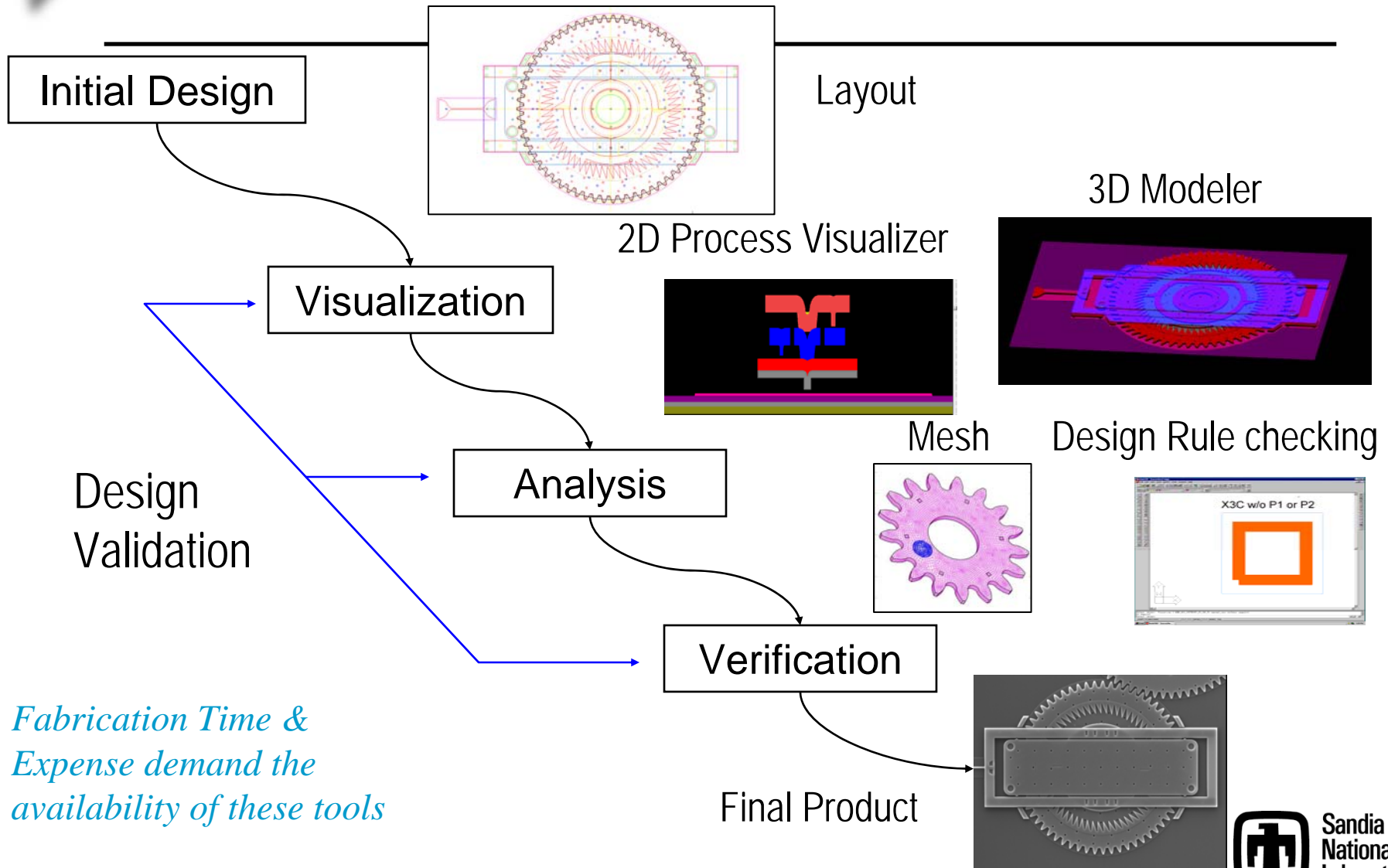
J. Allen, Sandia National Laboratories



Comtois, 1996



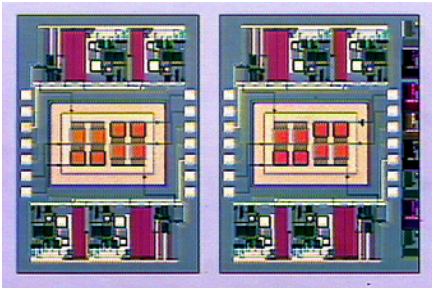
CAD Tools are Essential to the Design of Microsystems



Reliability Concerns Increase With Complexity

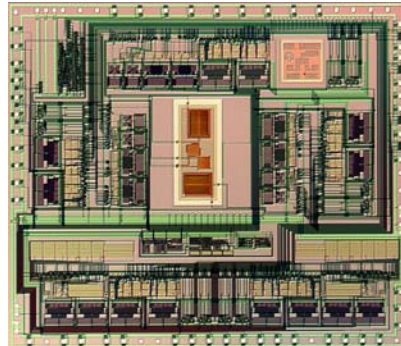
Class I

- No Moving Parts
- e.g., Pressure Sensors*



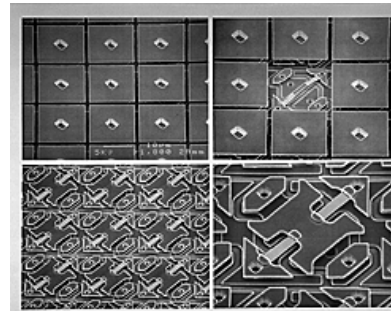
Class II

- Moving Parts
- e.g., Accelerometers*



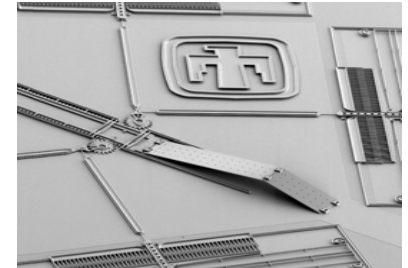
Class III

- Moving Parts
 - Impacting Surfaces
- e.g., Tilting Mirrors*

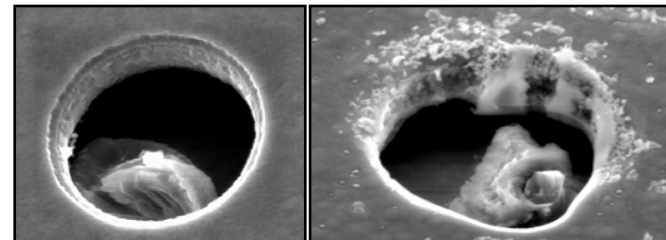
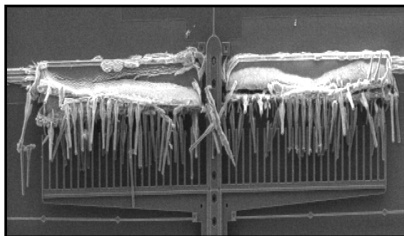


Class IV

- Moving Parts
 - Impacting Surfaces
 - Rubbing Surfaces
- e.g., Gears*

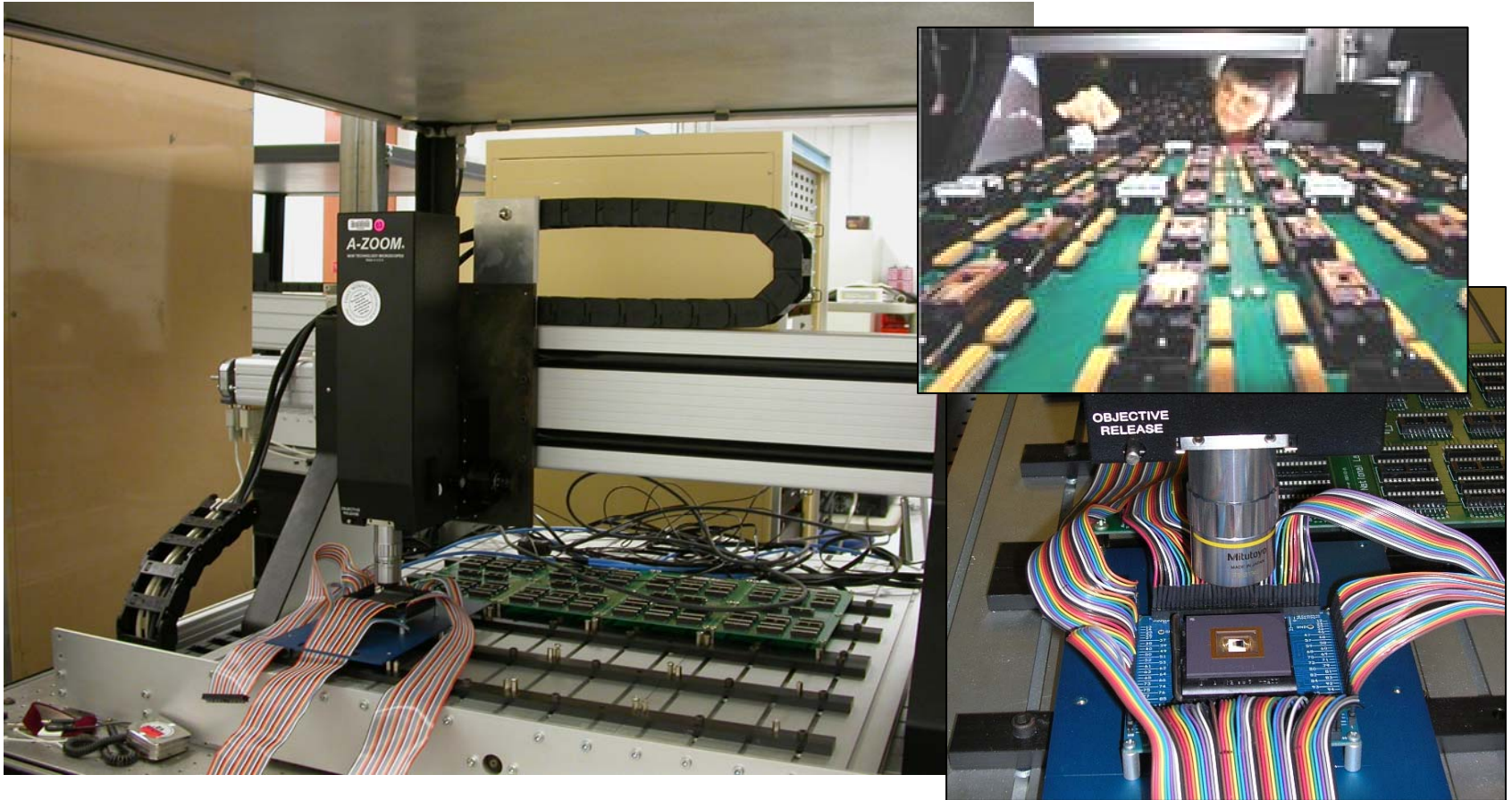


Understand the science of reliability



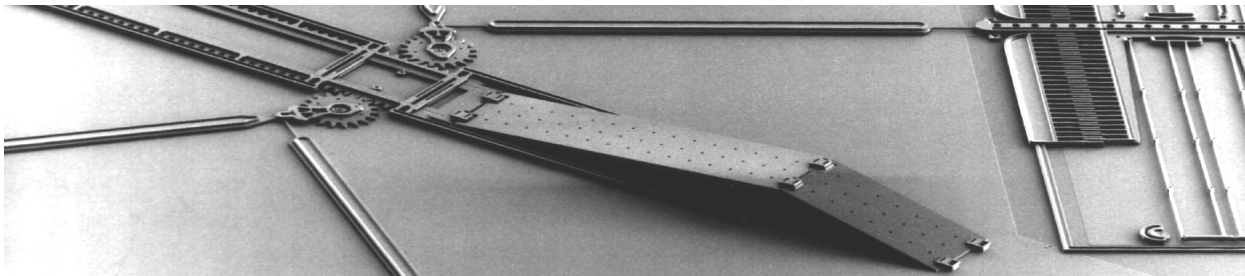
Reliability Testing

Sandia High-volume Micromachine Measurement of Reliability



MEM Performance Measurement Issues

- These are **small devices** (microns)
- Structures may **move very fast** (>1 kHz, >100000 rpm)
- **Small displacements** can occur (angstroms - microns)
- Displacements can be **in plane** or **out of plane**
- **High voltages** may be required (many 10s of volts)
- **Complex control signals** may be necessary
- Direct electrical measurements are **not typical**



MEMS Electrical Contacts

- **Contact Resistance is a function of Contact Force**
 - An issue at Microscale
- **Materials issues**
 - Contact Stiction
 - Contact Resistance change with age and repeated actuation

J. Actuators 73 (1999) 138–143

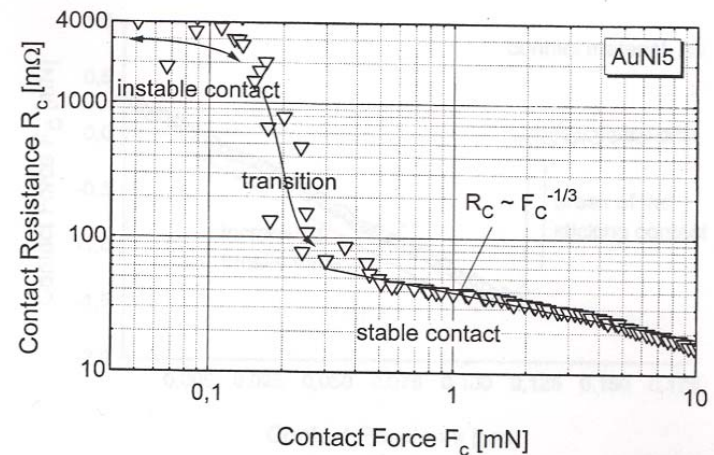
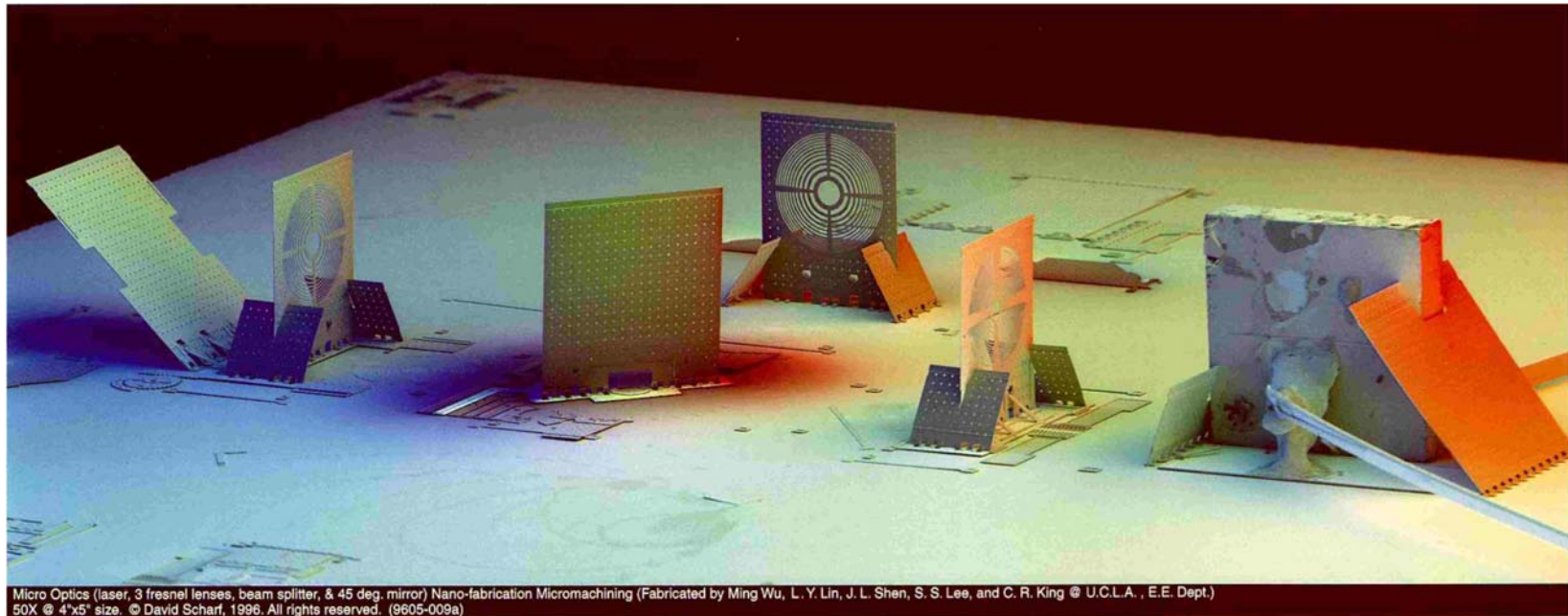


Fig. 4. $R_c - F_c$ characteristics of closing AuNi5 contacts: unstable contact at very low force, transition to lower resistance and the domain of stable contact with the measured resistance force characteristic compared to theoretical relationship according to Holm's model, from Ref. [6].

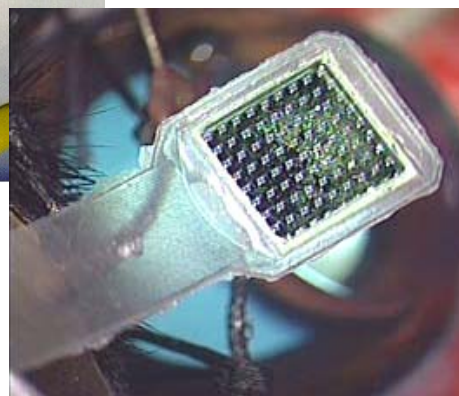
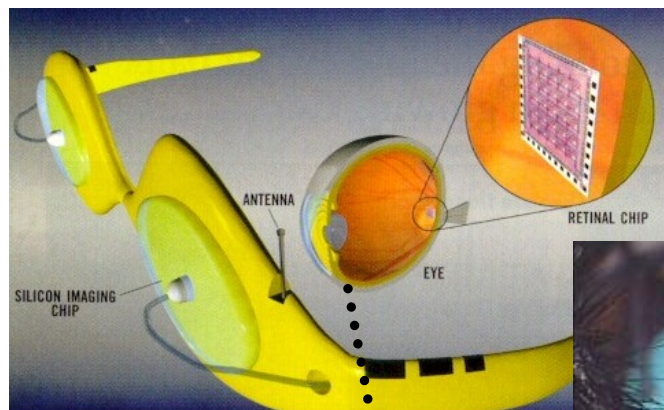
Optical Bench Example



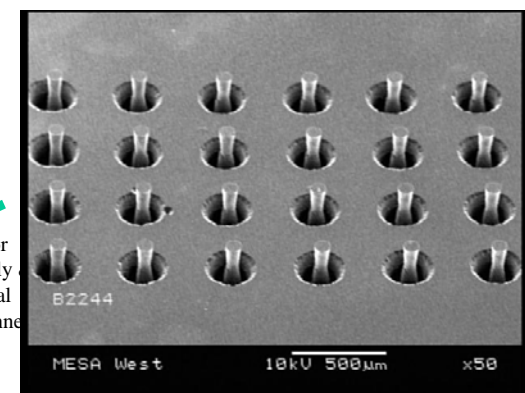
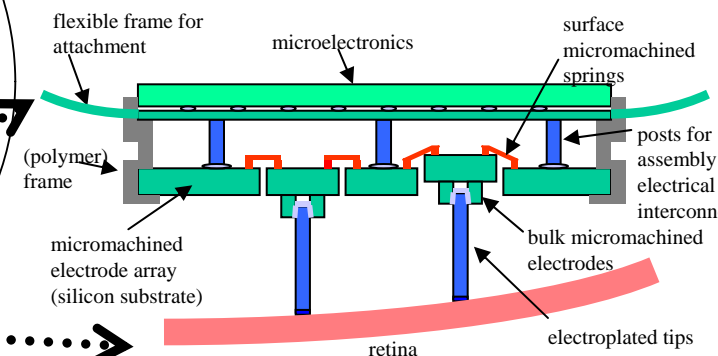
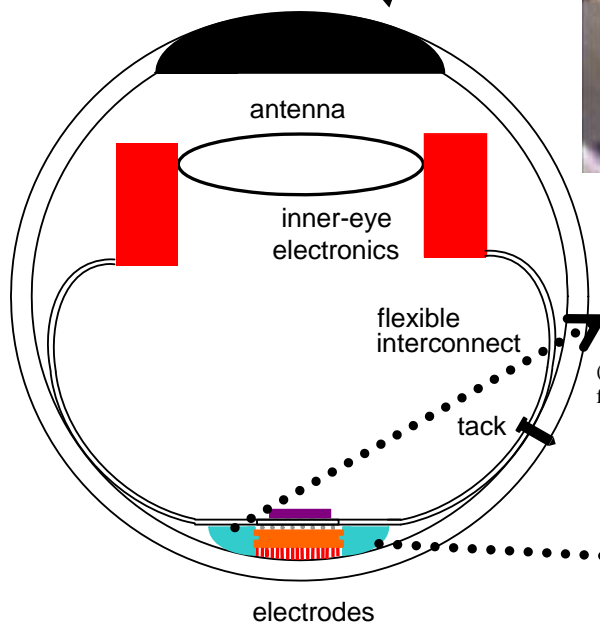
Laser, 3 Fresnel lenses, beam splitter, 45 degree mirror

Dr. Wu, U. of California, Berkley

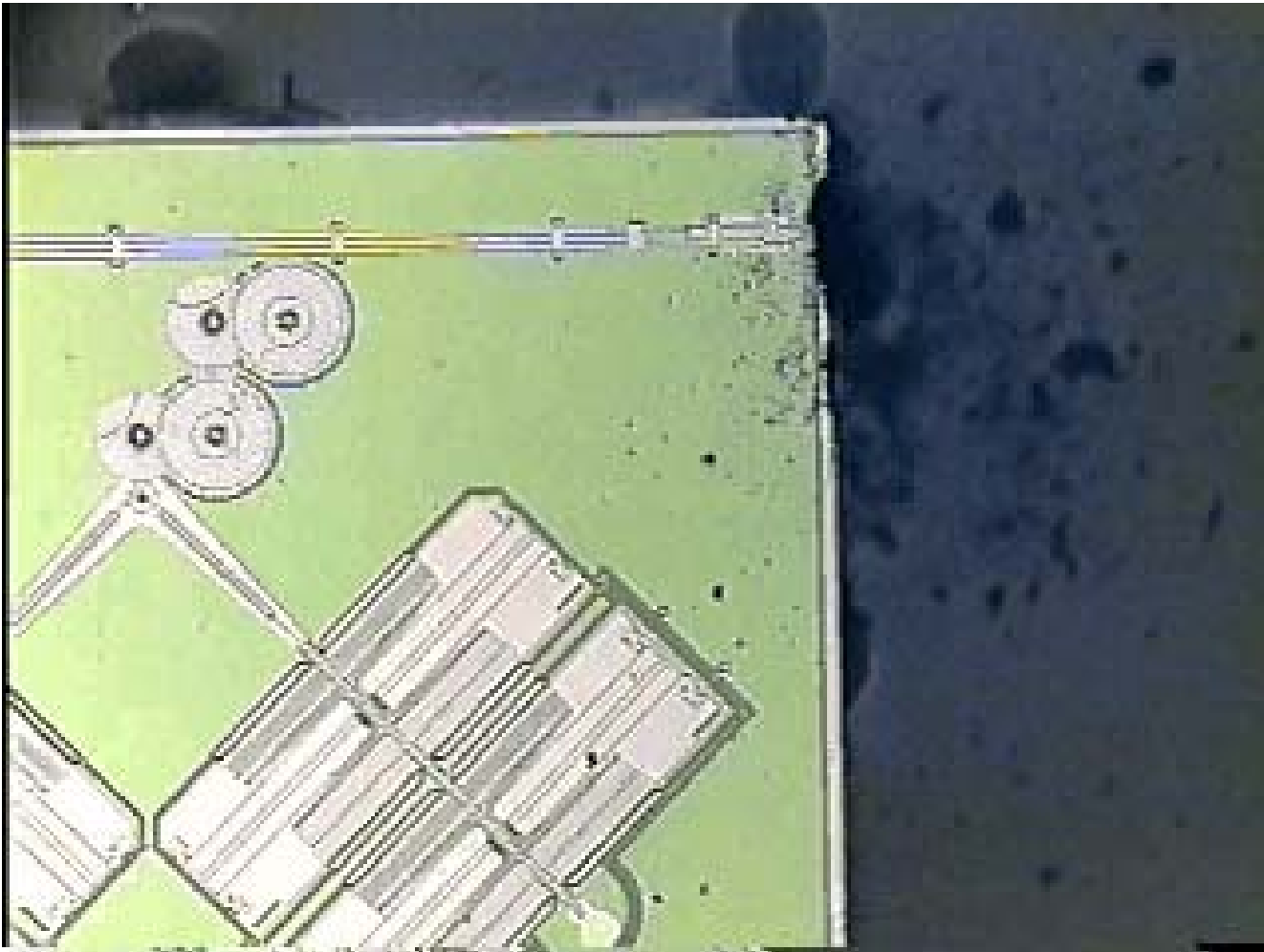
Retinal Implant



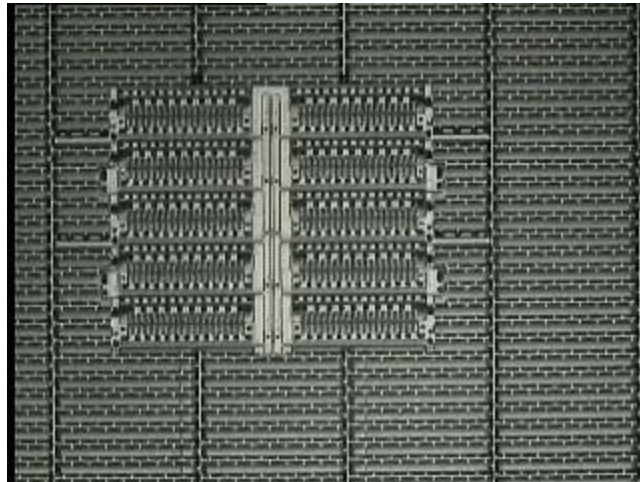
- Electrical stimulation of retinal neurons after light sensitive cells (photoreceptors) are lost.
- Micromachined conformal electrode array provides positive controlled contact with tissue (retina), accommodating overall and local curvature.
- Integrated electronics essential for high electrode count system (on-chip mux/demux for 100+).
- Mechanical test modules in animal tests.



Neural Probes

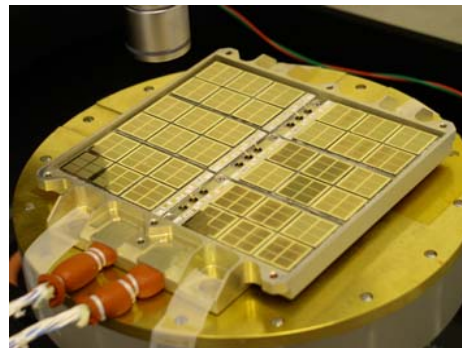


MEMS Variable Emittance Louvers

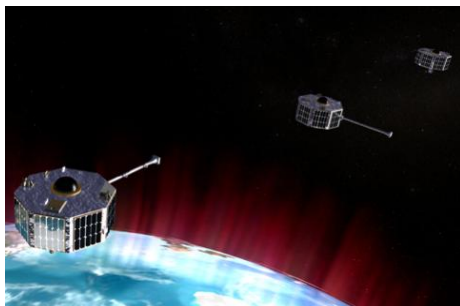


2592 SUMMiT V™ die
with Buried Interconnects

4"x4" Johns Hopkins/APL
Experimental Thermal
Regulator



3 NASA/Goodard
ST5 Microsats
Launched 3/22/06

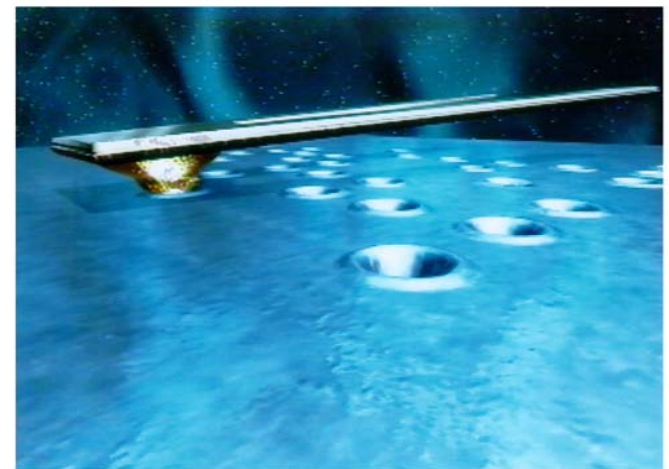
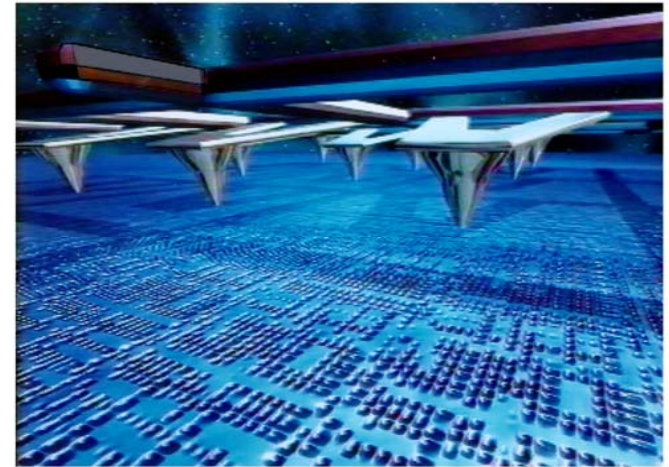
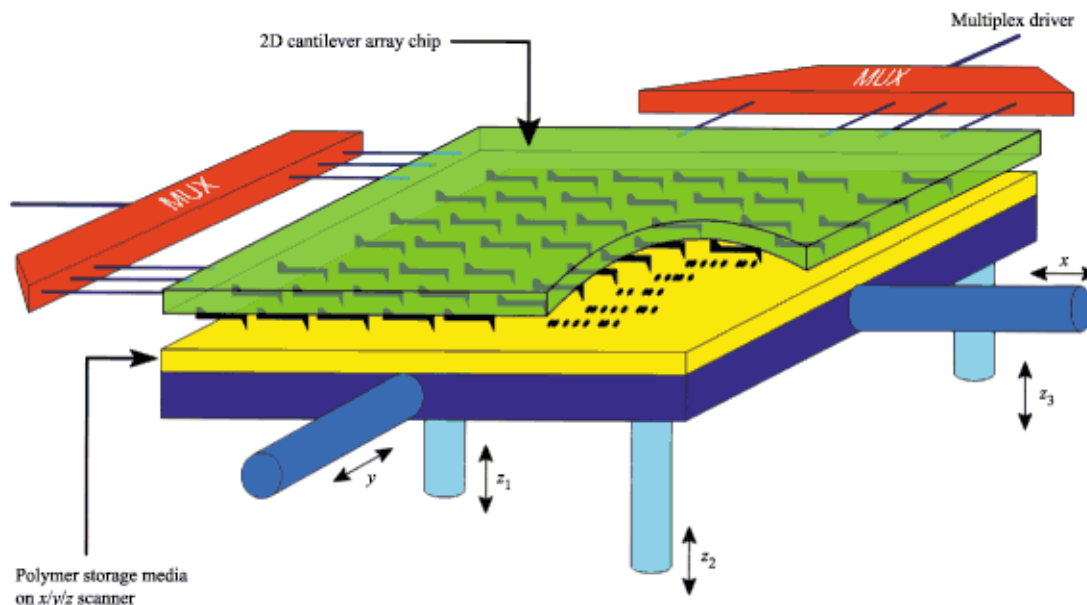


Experimental satellites
monitor space weather

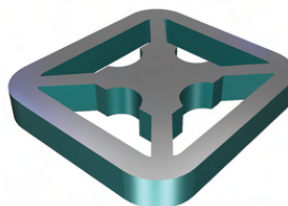


IBM Millipede Storage System

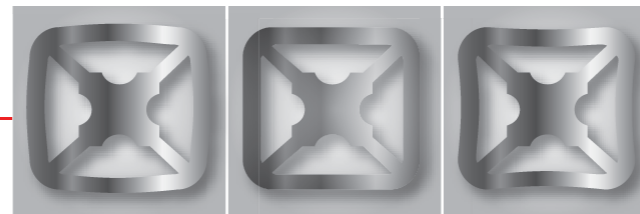
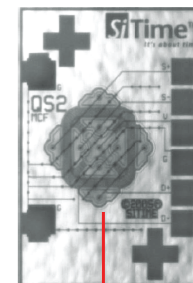
- High density data storage possible(Tb/in^2)
- 4x Magnetic Media
- AFM tip writes and reads data
- Bit set by melting depression into polymer medium



SiTime Resonators

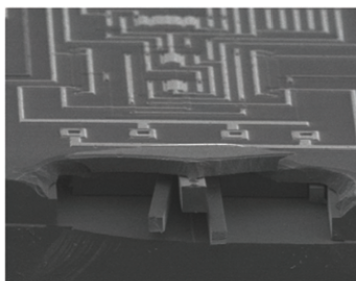


SiTime's revolutionary MEMS First™ technology allows ultra stable mechanical resonators to be integrated into standard silicon chips with performance as good as or better than traditional quartz-based systems.



SiRes™ mechanical resonator vibrating.

Single crystal Si encapsulation layer allows CMOS integration



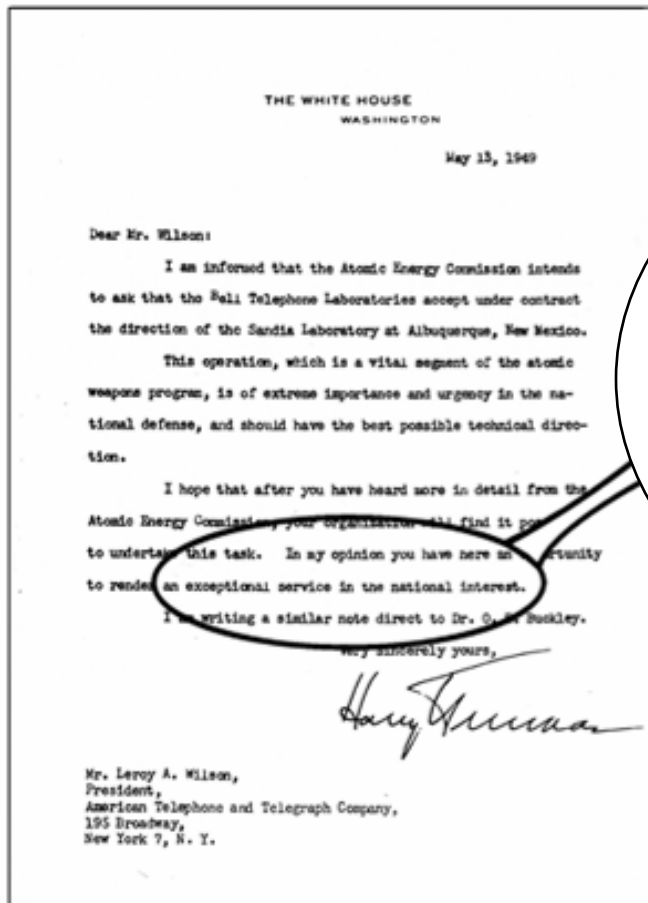


PRISM Center can greatly Impact Microsystem Development

- **Improve understanding MEMS reliability**
- **Provide the capability for analysis based design versus empirical or design of experiments approach**
- **Provide the ability to include uncertainty of fabrication process and materials in MEMS designs**
- **Increased understanding of the physics of phenomena.**

Sandia was established in 1949 to serve the national defense needs of the nation

“Exceptional Service in the National Interest”



I hope that after you have heard more
in detail from the Atomic Energy Commission,
your organization will find it possible to undertake this task.

**In my opinion you have here an opportunity to
render an exceptional service in the national interest.**

I am writing a similar note direct to Dr. O. E. Buckley.

Very sincerely yours,
Harry Truman

Sandia is a National Security Laboratory

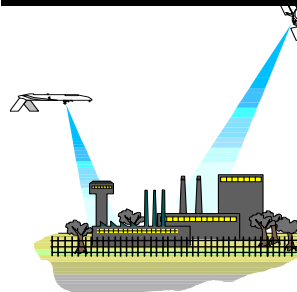
Sustain Nuclear Weapons Stockpile



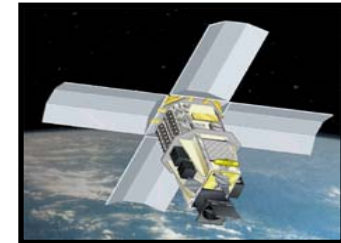
Safe, Secure,
Reliable Weapons



Reduce Vulnerability to Weapons of Mass Destruction



Detection



Surveillance

Advance Surety of Global Infrastructures



Energy



Information



Transportation

Enhance National Security Measures



Architectural
Surety

Anti-crime and anti-terrorism
technology



Smart Weapons



Sandia
National
Laboratories

Sandia – in round numbers

- 8,600 full-time employees
 - ~7,700 in New Mexico
 - ~ 900 in California
- 800 buildings, 6.1M square feet
- 1,500 Ph.D.'s, 2,700 Masters
 - 53% engineering
 - 20% science and mathematics
 - 16% computing
 - 6% other fields
- Annual budget >\$2 Billion

